

VS-15ETX06S-M3, VS-15ETX06-1-M3

Vishay Semiconductors

Hyperfast Rectifier, 15 A FRED Pt[®]

2 3 D²PAK (TO-263AB) **TO-262AA** Base Cathode റ 2 02 **3** ქ 3 <u>ქ</u> N/C N/C Anode Anode VS-15ETX06-1-M3 **VS-15ETX06S-M3**

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PRIMARY CHARACTERISTICS								
I _{F(AV)}	15 A							
V _R	600 V							
V _F at I _F	1.5 V							
t _{rr} (typ.)	18 ns							
T _J max.	175 °C							
Package	D ² PAK (TO-263AB), TO-262AA							
Circuit configuration	Single							

FEATURES

- Benchmark ultralow forward voltage drop
- Hyperfast recovery time
- · Low leakage current
- 175 °C operating junction temperature
- Meets MSL level 1, per J-STD-020, LF maximum peak of 245 °C
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

DESCRIPTION / APPLICATIONS

State of the art hyperfast recovery rectifiers designed with optimized performance of forward voltage drop, hyperfast recovery time, and soft recovery.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in PFC boost stage in the AC/DC section of SMPS, inverters or as freewheeling diodes.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

ABSOLUTE MAXIMUM RATINGS								
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS				
Peak repetitive reverse voltage	V _{RRM}		600	V				
Average rectified forward current	I _{F(AV)}	T _C = 133 °C	15					
Non-repetitive peak surge current	I _{FSM}	T _J = 25 °C	170	А				
Peak repetitive forward current	I _{FM}		30					
Operating junction and storage temperatures	T _J , T _{Stg}		-65 to +175	°C				

ELECTRICAL SPECIFIC		$T_J = 25 \text{ °C}$ unless otherwise specified)				
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	V _{BR} , V _R	I _R = 100 μA	600	-	-	
Forward voltage	V _F	I _F = 15 A	-	2.3	3.2	V
Forward voltage	VF	I _F = 15 A, T _J = 150 °C	-	1.5	1.8	
Povorao lookogo ourront		$V_R = V_R$ rated	-	0.1	50	
Reverse leakage current	I _R	$T_J = 150 \text{ °C}, V_R = V_R \text{ rated}$	-	40	300	- V 3.2 V 1.8 50 µA
Junction capacitance	CT	V _R = 600 V	-	20	-	pF
Series inductance	L _S	Measured lead to lead 5 mm from package body	-	8.0	-	nH

Revision: 21-Dec-2021



HALOGEN

FREE

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DYNAMIC RECOVERY CHA	RACTERI	STICS (T _C = 25 °C	unless otherwise s	pecified)	1		
PARAMETER	SYMBOL	TEST CC	NDITIONS	MIN.	TYP.	MAX.	UNITS
		$I_F = 1 \text{ A}, \ dI_F/dt = 100$	A/ μ s, V _R = 30 V	-	18	22	
Boyono rocovory timo	+	$I_F = 15 \text{ A}, \text{ d}I_F/\text{d}t = 10$	0 A/µs, V _R = 30 V	-	20	32	
Reverse recovery time	۲r	T _J = 25 °C		-	22	-	115
		T _J = 125 °C		-	52	-	
Deals receivers ourrent	1	T _J = 25 °C	$I_{\rm F} = 15 {\rm A}$	-	2.4	-	^
Peak recovery current	IRRM	T _J = 125 °C	dl _F /dt = 200 A/µs V _B = 390 V	-	5.1	-	A
	0	T _J = 25 °C		-	25	-	UNITS ns A nC ns A
Reverse recovery charge	Q _{rr}	T _J = 125 °C		-	150	-	
Reverse recovery time	t _{rr}		I _F = 15 A	-	37	-	ns
Peak recovery current	I _{RRM}	T _J = 125 °C	dI _F /dt = 800 A/µs	-	16	-	Α
Reverse recovery charge			V _R = 390 V	-	350	-	nC

THERMAL - MECHANICA	L SPECIFIC	ATIONS				
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	T _J , T _{Stg}		-65	-	175	°C
Thermal resistance, junction to case per leg	R _{thJC}		-	1.0	1.3	
Thermal resistance, junction to ambient per leg	R _{thJA}	Typical socket mount	-	-	70	°C/W
Thermal resistance, case to heatsink	R _{thCS}	Mounting surface, flat, smooth, and greased	-	0.5	-	
Waisht			-	2.0	-	g
Weight			-	0.07	-	oz.
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)
Marking daylog		Case style D ² PAK (TO-263AB)		15ET	X06S	'5 °C 3
Marking device		Case style TO-262AA		15ET	X06-1	



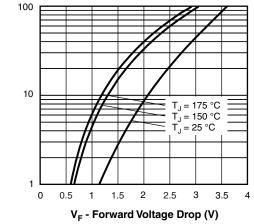


Fig. 1 - Typical Forward Voltage Drop Characteristics

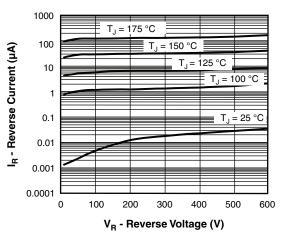
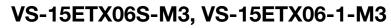


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

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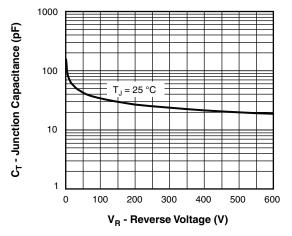


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

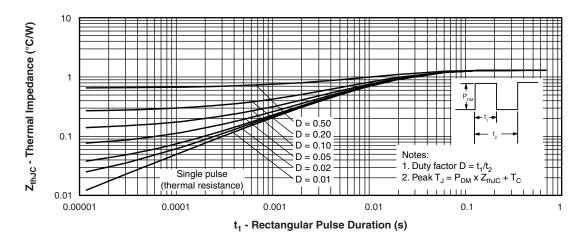


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

Average Power Loss (W)

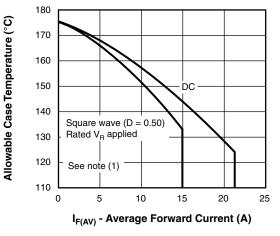


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

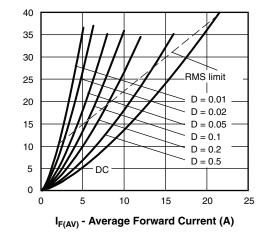


Fig. 6 - Forward Power Loss Characteristics

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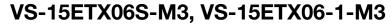
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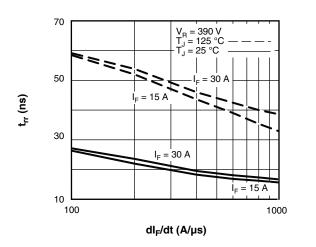
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Fig. 7 - Typical Reverse Recovery Time vs. dl_F/dt



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⁽¹⁾ Formula used: $T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}$;

Pd = forward power loss = $I_{F(AV)} \times V_{FM}$ at ($I_{F(AV)}/D$) (see fig. 6); Pd_{REV} = inverse power loss = $V_{R1} \times I_R$ (1 - D); I_R at V_{R1} = rated V_R

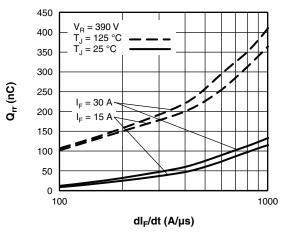


Fig. 8 - Typical Stored Charge vs. dl_F/dt

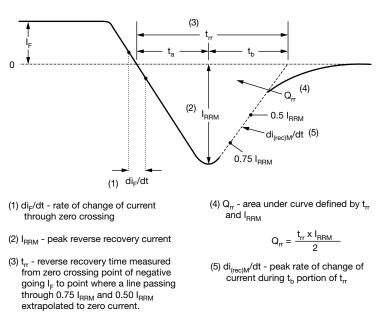


Fig. 9 - Reverse Recovery Waveform and Definitions

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VS-15ETX06S-M3, VS-15ETX06-1-M3

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ORDERING INFORMATION TABLE

Device code	VS-	15	Е	т	x	06	S	TRL	-M3
		2	3	4	5	6	7	8	9
	(T)				toro re-	aduat			
			-	niconduo		Jauci			
	2 -			ng (15 A Nicdo	\)				
	뜨		single o						
	4 -), D ² PAł	•	03AB)			
	5 -			ist recov	-				
	6 -		-	ing (06 =	-)			
	7 -	• \$	= D ² PA	К (ТО-2	263AB)				
		• -1	= TO-2	62AA					
	8 -	• N	one = tu	ibe (50 p	pieces)				
		• TI	RL = tap	e and re	eel (left	oriented	l, for D ²	² PAK (T	O-263A
		• TI	R = ta	be and r	eel (righ	nt orient	ed, for l	D ² PAK (TO-263
	9 -			ntal digit:				·	x

-N	13 = halogen-free,	RoHS-compliant,	and terminations I	lead (Pb)-free

ORDERING INFORMATION (Example)							
PREFERRED P/N	BASE QUANTITY	PACKAGING DESCRIPTION					
VS-15ETX06S-M3	50	Antistatic plastic tubes					
VS-15ETX06STRR-M3	800	13" diameter plastic tape and reel					
VS-15ETX06STRL-M3	800	13" diameter plastic tape and reel					
VS-15ETX06-1-M3	50	Antistatic plastic tubes					

LINKS TO RELATED DOCUMENTS								
Dimensions	D ² PAK (TO-263AB)	www.vishay.com/doc?96164						
Dimensions	TO-262	www.vishay.com/doc?96165						
Part marking information	D ² PAK (TO-263AB)	www.vishay.com/doc?95444						
Fart marking mornation	TO-262	www.vishay.com/doc?95443						
Packaging information		www.vishay.com/doc?96424						

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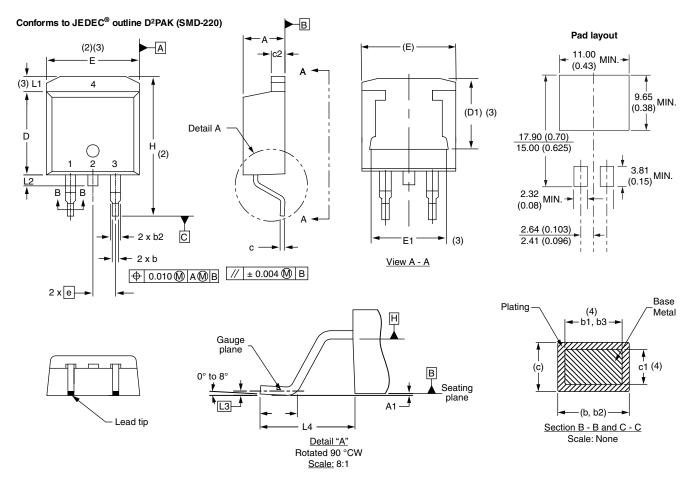


Outline Dimensions

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D²PAK

DIMENSIONS in millimeters and inches



SYMBOL	ETERS	INCHES		NOTES	SYMBOL	MILLIMETERS		INCHES		NOTES		
STMBUL	MIN.	MAX.	MIN.	MAX.	NOTES		STMBOL	MIN.	MAX.	MIN.	MAX.	NOTES
А	4.06	4.83	0.160	0.190			D1	6.86	8.00	0.270	0.315	3
A1	0.00	0.254	0.000	0.010			Е	9.65	10.67	0.380	0.420	2, 3
b	0.51	0.99	0.020	0.039			E1	7.90	8.80	0.311	0.346	3
b1	0.51	0.89	0.020	0.035	4		е	2.54	BSC	0.100	BSC	
b2	1.14	1.78	0.045	0.070			Н	14.61	15.88	0.575	0.625	
b3	1.14	1.73	0.045	0.068	4		L	1.78	2.79	0.070	0.110	
С	0.38	0.74	0.015	0.029			L1	-	1.65	-	0.066	3
c1	0.38	0.58	0.015	0.023	4		L2	1.27	1.78	0.050	0.070	
c2	1.14	1.65	0.045	0.065			L3	0.25	BSC	0.010	BSC	
D	8.51	9.65	0.335	0.380	2		L4	4.78	5.28	0.188	0.208	

Notes

⁽¹⁾ Dimensioning and tolerancing per ASME Y14.5 M-1994

(2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body

(3) Thermal pad contour optional within dimension E, L1, D1 and E1

⁽⁴⁾ Dimension b1 and c1 apply to base metal only

⁽⁵⁾ Datum A and B to be determined at datum plane H

⁽⁶⁾ Controlling dimension: inches

⁽⁷⁾ Outline conforms to JEDEC[®] outline TO-263AB

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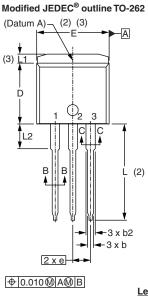


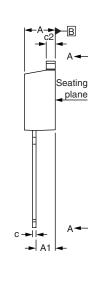
Outline Dimensions

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TO-262AA

DIMENSIONS in millimeters and inches



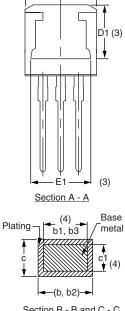


Lead assignments

Lead tip



1. - Anode (two die)/open (one die) 2., 4. - Cathode 3. - Anode



F

Section B - B and C - C Scale: None

SYMBOL	MILLIN	IETERS	INC	NOTES	
	MIN.	MAX.	MIN.	MAX.	NOTES
А	4.06	4.83	0.160	0.190	
A1	2.03	3.02	0.080	0.119	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
С	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
е	2.54	BSC	0.100) BSC	
L	13.46	14.10	0.530	0.555	
L1	-	1.65	-	0.065	3
L2	3.56	3.71	0.140	0.146	

Notes

 (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
 (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body (3)

Thermal pad contour optional within dimension E, L1, D1 and E1

⁽⁴⁾ Dimension b1 and c1 apply to base metal only (5)

Controlling dimension: inches Outline conform to JEDEC[®] TO-262 except A1 (max.), b (min., max.), b1 (min.), b2 (max.), c (min.), c1(min.), c2 (max.), D (min.), E (max.), (6) L1 (max.), L2 (min., max.)

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